

## ABSTRACT OF THE DISCLOSURE

A device manufacturing method, including: a first process for providing the  
5 plural elements on the original substrate via a separation layer in a condition where  
terminal sections are exposed to a surface on an opposite side to the separation layer; a  
second process for adhering the surface where the terminal sections of the elements to be  
transferred on the original substrate are exposed, via conductive adhesive, to a surface of  
the final substrate on a side where conductive sections for conducting with the terminal  
10 sections of the elements are provided; a third process for producing exfoliation in the  
separation layer between the original substrate and the final substrate; and a fourth  
process for separating the original substrate from which the transfer of elements has been  
completed, from the final substrate.